

ADC168M102R-SEP Single-Event Latch-Up (SEL) Radiation Report



ABSTRACT

The purpose of this study is to characterize the effects of heavy-ion irradiation on the single-event latch-up (SEL) performance of the ADC168M102R-SEP, dual 16-bit analog-to-digital converter (ADC). Heavy- ions with an LET_{EFF} of 48MeV-cm²/mg were used to irradiate the devices with a fluence of 1×10^7 ions/cm². The results demonstrate that the ADC168M102R-SEP is SEL-free up to LET_{EFF} = 48MeV-cm²/mg at 125°C.

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1 Overview

The ADC168M102R-SEP is a radiation-tolerant dual, 16-bit, 1MSPS analog-to-digital converter (ADC) with eight pseudo- or four fully-differential input channels grouped into two pairs for simultaneous signal acquisition.

The analog inputs are maintained differentially to the input of the ADC. The input multiplexer can be used in either pseudo-differential mode, supporting up to four channels per ADC (4x2), or in fully-differential mode that allows to convert up to two inputs per ADC (2x2).

The ADC168M102R-SEP offers two programmable reference outputs, flexible supply voltage ranges, a programmable auto-sequencer, data storage of up to four conversion results per channel, and several power-down features.

Table 1-1. Overview Information (1)

DESCRIPTION	DEVICE INFORMATION
TI part number	ADC168M102R-SEP
MLS number	ADC168M102RRHBTSEP
Device function	Radiation-tolerant, 16-bit ADC
Technology	HPA07
Exposure facility	Radiation Effects Facility, Cyclotron Institute, Texas A&M University
Heavy ion fluence per run	$1 \times 10^6 - 1 \times 10^7$ ions/cm ²
Irradiation temperature	125°C (for SEL testing)

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2 SEE Mechanisms

The primary single-event effect (SEE) event of interest in the ADC168M102R-SEP is the destructive single-event latch-up (SEL). From a risk and impact point-of-view, the occurrence of an SEL is potentially the most destructive SEE event and the biggest concern for space applications. The HPA07 process node was used for the ADC168M102R-SEP. SEL can occur if excess current injection caused by the passage of an energetic ion is high enough to trigger the formation of a parasitic cross-coupled PNP and NPN bipolar structure (formed between the p-sub and n-well and n+ and p+ contacts). The parasitic bipolar structure initiated by a single-event creates a high-conductance path (inducing a steady-state current that is typically orders-of-magnitude higher than the normal operating current) between power and ground that persists (is *latched*) until power is removed or until the device is destroyed by the high-current state.

This study was performed to evaluate the SEL effects with a bias voltage of 5.5V on AVDD and 3.6V on DVDD. Heavy ions with $LET_{EFF} = 48\text{MeV}\cdot\text{cm}^2/\text{mg}$ were used to irradiate the devices. Flux of 10^5 ions/s- cm^2 and fluence of 10^7 ions/ cm^2 were used during the exposure at 125°C temperature.

Figure 2-1 shows a functional block diagram for this device.

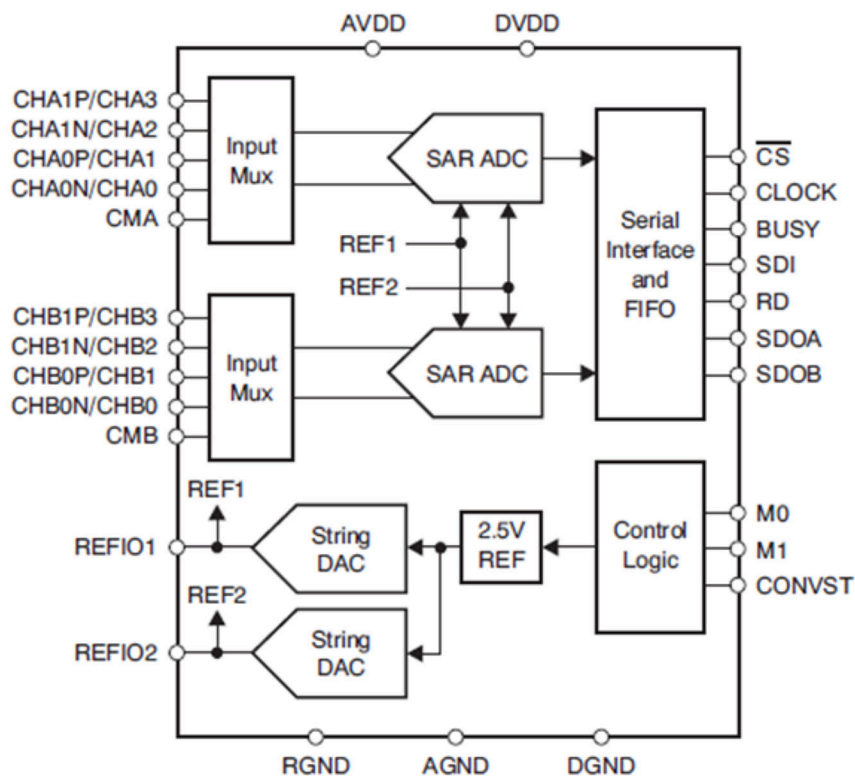


Figure 2-1. Functional Block Diagram of the ADC168M102R-SEP

3 Test Device and Test Board Information

The ADC168M102R-SEP is packaged in a 32-pin RHB (VQFN) shown with the pinout in [Figure 3-1](#). [Figure 3-2](#) shows the biasing configuration used for both the SEL and SET tests.

ADC168M102R-SEP pinout diagram. The package was decapped to reveal the die face for all heavy ion testing.

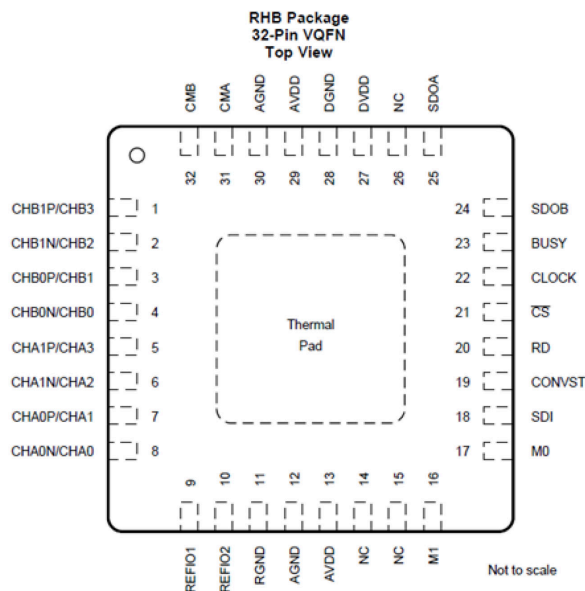


Figure 3-1. ADC168M102R-SEP Pinout Diagram

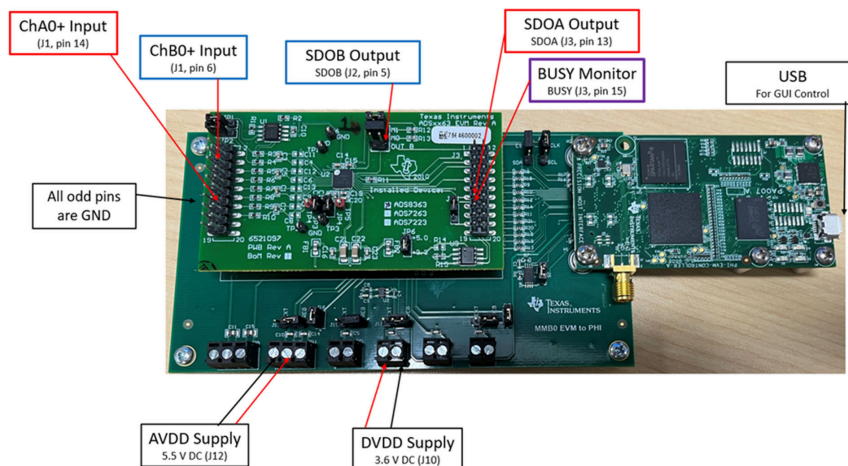


Figure 3-2. ADC168M102R-SEP Bias Configuration

4 Irradiation Facility and Setup

The heavy ion species used for the SEE studies on this product were provided and delivered by the TAMU Cyclotron Radiation Effects Facility using a superconducting cyclotron and advanced electron cyclotron resonance (ECR) ion source. Ion beams are delivered with high uniformity over a 1-inch diameter circular cross-sectional area for the in-air station. Uniformity is achieved by means of magnetic defocusing. The intensity of the beam is regulated over a broad range spanning several orders of magnitude. For the bulk of these studies, ion fluxes between 10^4 and 10^5 ions/s-cm² were used to provide heavy ion fluences between 10^6 and 10^7 ions/cm². For these experiments Silver (Ag) ions were used. Ion beam uniformity for all tests was in the range of 91% to 98%.

5 Single-Event Latch-Up Results

During SEL characterization, the device was heated using forced hot air, maintaining the device temperature at 125°C. The temperature was monitored by means of a K-type thermocouple attached as close to the device as possible. The species used for SEL testing was a silver (⁴⁷Ag) ion with an angle-of-incidence of 0° for an LET_{EFF} = 48MeV-cm²/mg. The kinetic energy in the vacuum for this ion is 1.634GeV (15-MeV/amu line). A flux of approximately 10⁵ ions/s-cm² and a fluence of approximately 10⁷ ions/cm were used for two runs. The external voltage with the highest recommended voltage setting of 5.5V is applied onboard AVDD connector. The run duration to achieve this fluence was approximately two minutes. As shown in Table 5-1, no SEL events were observed during the exposure of 3 EVM boards completing two runs each. Figure 5-1 shows the current plots during beam exposure.

Table 5-1. ADC168M102R-SEP SEL Conditions Using 47Ag at an Angle-of-Incidence of 0°

Board #	DISTANCE (mm)	TEMPERATURE (°C)	ION	ANGLE	FLUX (ions × cm ² /mg)	FLUENCE (# ions)	LETEFF (MeV.cm ² /mg)
1	40	125	Ag	0°	1.00E+05	1.00E+07	48
2	40	125	Ag	0°	1.00E+05	1.00E+07	48
3	40	125	Ag	0°	1.00E+05	1.00E+07	48

No SEL events were observed, indicating that the ADC168M102R-SEP is SEL-immune at LET_{EFF} = 48MeV-cm²/mg and T = 125°C. Using the MFTF method described in Appendix A and combining (or summing) the fluences of the three runs at 125°C (1 × 10⁷), the upper-bound cross section (using a 95% confidence level) is calculated in Equation 1:

$$\sigma_{SEL} \leq 1.84 \times 10^{-7} \text{ cm}^2 \tag{1}$$

where:

- LET_{EFF} = 48 MeV-cm²/mg
- T = 125°C

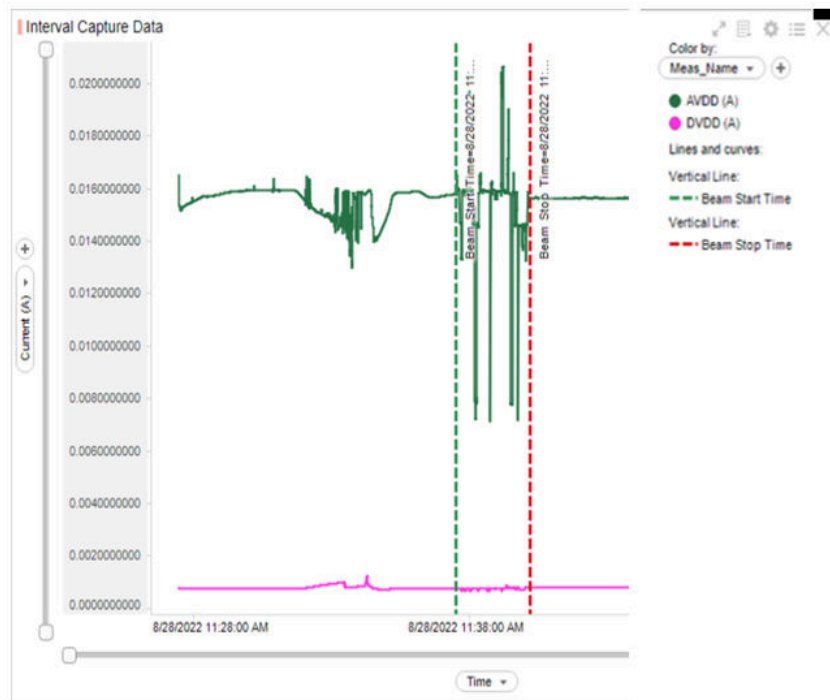


Figure 5-1. AVDD and DVDD Transients During Run #1

6 Summary

Radiation effects on the radiation-tolerant, full featured, general purpose, 16-bit analog-to-digital converter (ADC) ADC168M102R-SEP, was studied. This device passed a total dose rate of up to 30krad(Si) and is latch-up immune up to $LET_{EFF} = 48\text{MeV}\cdot\text{cm}^2/\text{mg}$ and $T = 125^\circ\text{C}$.

7 Confidence Interval Calculations

For conventional products where hundreds of failures can occur during a single exposure, the average failure rate of devices can be determined by being tested in a heavy-ion beam as a function of fluence with a high degree of certainty and reasonably tight standard deviation, and thus obtain a good deal of confidence that the calculated cross section is accurate.

With radiation-hardened parts however, determining the cross section is difficult because often few or no failures are observed during an entire exposure. Determining the cross section using an average failure rate with standard deviation is no longer a viable option, and the common practice of assuming a single error occurred at the conclusion of a null-result can end up in a greatly underestimated cross section.

In cases where observed failures are rare or non-existent, using confidence intervals and the chi-squared distribution is indicated. The chi-squared distribution is particularly well-suited for the determination of a reliability level when the failures occur at a constant rate. In the case of SEE testing where the ion events are random in time and position within the irradiation area, a failure rate is expected that is independent of time (presuming that parametric shifts induced by the total ionizing dose do not affect the failure rate), and thus the use of chi-squared statistical techniques is valid (because events are rare, an exponential or Poisson distribution is usually used).

In a typical SEE experiment, the device-under-test (DUT) is exposed to a known, fixed fluence (ions/cm^2) and the DUT is monitored for failures. This process is analogous to fixed-time reliability testing and, more specifically, time-terminated testing where the reliability test is terminated after a fixed amount of time whether or not a failure has occurred (in the case of SEE tests fluence is substituted for time and is therefore a fixed fluence test[5]). Calculating a confidence interval specifically provides a range of values that is likely to contain the parameter of interest (the actual number of failures per fluence). Confidence intervals are constructed at a specific confidence level. For example, a 95% confidence level implies that if a given number of units were sampled numerous times and a confidence interval estimated for each test, the resulting set of confidence intervals brackets the true population parameter in approximately 95% of the cases.

To estimate the cross section from a null-result (no fails observed for a given fluence) with a confidence interval, start with the standard reliability determination of the lower-bound (minimum) mean-time-to-failure for fixed-time testing (an exponential distribution is assumed) in [Equation 2](#):

$$MTTF = \frac{2nT}{\chi^2_{2(d+1); 100(1 - \frac{\alpha}{2})}} \quad (2)$$

where:

- MTTF is the minimum (lower-bound) mean-time-to-failure
- n is the number of units tested (presuming each unit is tested under identical conditions)
- T is the test time
- χ^2 is the chi-square distribution evaluated at $100(1 - \alpha / 2)$ confidence level
- d is the degrees-of-freedom (the number of failures observed)

With slight modification to this equation for the purposes of this test, invert the inequality and substitute F (fluence) in the place of T, as shown in [Equation 3](#):

$$MTTF = \frac{2nF}{\chi^2_{2(d+1); 100(1 - \frac{\alpha}{2})}} \quad (3)$$

where:

- MFTF is mean-fluence-to-failure
- F is the test fluence
- χ^2 is the chi-square distribution evaluated at $100(1 - \alpha / 2)$ confidence

- d is the degrees-of-freedom (the number of failures observed)

The inverse relation between MTTF and failure rate is mirrored with the MFTF. Thus, the upper-bound cross section is obtained by inverting the MFTF as shown in Equation 4:

$$\sigma = \frac{\chi^2_2(d+1); 100(1-\frac{\alpha}{2})}{2nF} \tag{4}$$

Assume that all tests are terminated at a total fluence of 106 ions/cm². Also assume there are a number of devices with very different performances that are tested under identical conditions. Assume a 95% confidence level ($\sigma = 0.05$). When d increases from 0 events to 100 events, the actual confidence interval becomes smaller, indicating that the range of values of the true value of the population parameter (in this case the cross section) is approaching the mean value + 1 standard deviation. This difference makes sense when considering that as more events are observed the statistics are improved such that uncertainty in the actual device performance is reduced.

Table 7-1. Experimental Example Calculation of MFTF and σ Using a 95% Confidence Interval (1)

Degrees-of-Freedom (d)	2(d + 1)	χ^2 at 95%	Calculated Cross Section (cm ²)		
			Upper-Bound at 95% Confidence	Mean	Average + Standard Deviation
0	2	7.38	3.69E-06	0.00E+00	0.00E+00
1	4	11.14	5.57E-06	1.00E-06	2.00E-06
2	6	14.45	7.22E-06	2.00E-06	3.41E-06
3	8	17.53	8.77E-06	3.00E-06	4.73E-06
4	10	20.48	1.02E-05	4.00E-06	6.00E-06
5	12	23.34	1.17E-05	5.00E-06	7.24E-06
10	22	36.78	1.84E-05	1.00E-05	1.32E-05
50	102	131.84	6.59E-05	5.00E-05	5.71E-05
100	202	243.25	1.22E-04	1.00E-04	1.10E-04

1. Using a 95% confidence interval for several different observed results (d = 0, 1, 2,...100 observed events during fixed-fluence tests) assuming 10⁶ ions/cm² for each test. When the number of observed events increases, the confidence interval approaches the mean.

8 References

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